

# **COPPER/COPPER ALLOY SURFACE BONDING PROMOTOR AND ITS USAGE**

## **ABSTRACT OF THE DISCLOSURE**

**5**           A halogen ion/hydrogen peroxide-free copper/copper alloy surface bonding promotor includes copper oxidant 0.1~20wt%, acidic solution prepared from organic acid, inorganic acid, or their compound 5~20wt%, and nonionic compound 0.001~10wt%. The use of the halogen ion/hydrogen peroxide-free copper/copper alloy

**10** surface bonding promotor enables the copper/copper alloy to have a rough surface that exhibits excellent adhesion to resins and superior solderability.